Amendments to the Claims:

1. (currently amended) A method for securing a printed circuit board to an aluminum rigidizer that serves as a heat sink, the method comprising steps of:

milling vents into the printed circuit board;

applying a liquid adhesive to the aluminum rigidizer;

applying a first cure to the liquid adhesive after application of the liquid adhesive to produce a liquid adhesive that is at least partially cured, wherein the first cure of the liquid adhesive produces a tacky adhesive;

placing the printed circuit board on the at least partially cured liquid adhesive;

screening a solder paste onto the printed circuit board;

placing components onto the solder paste on the printed circuit board; and

applying ~~heat~~ a second cure to the assembly of the components, printed circuit board, solder paste, at least partially cured adhesive, and rigidizer, wherein the applied heat reflows the solder paste to bond the components to the printed circuit board while simultaneously providing ~~a~~ the second cure, facilitated by the vents, to the at least partially cured liquid adhesive to produce a printed circuit board that is secured to the aluminum rigidizer; and

bending the printed circuit board and the aluminum rigidizer after the second cure of the at least partially cured liquid adhesive.

2. (previously presented) The method of claim 1, wherein the step of applying the liquid adhesive to the aluminum rigidizer comprises a step of screening the liquid adhesive onto the aluminum rigidizer.

3. (currently amended) The method of claim 1, wherein the step of applying a first cure to the liquid adhesive comprises a step of exposing selected areas of the liquid adhesive to a first curing element, and the step of applying the second cure to adhesive comprises exposing selected areas of the adhesive to a second curing element different than the first curing element.

4. (original) The method of claim 1, wherein the liquid adhesive is a dual-cure system adhesive.

5. (original) The method of claim 4, wherein the liquid adhesive is a B-stage epoxy.

6. (cancelled)

7. (previously presented) The method of claim 1, wherein the printed circuit board is flexible printed circuit board.

8-9. (cancelled)

10. (cancel)

11. (withdrawn) The method of claim 1, wherein the liquid adhesive can be cured by exposure to ultraviolet radiation.

12. (withdrawn) The method of claim 1, wherein the liquid adhesive can be cured by any one of a plurality of curing methods, wherein the first cure comprises applying a first curing method of the plurality of curing methods to the liquid adhesive and wherein the second cure comprises applying a second, different curing method of the plurality of curing methods to the liquid adhesive.

13-20. (cancelled)

21-23. (cancelled)

24-25. (cancelled)

26. (cancelled)

27. (withdrawn) The method of claim 21, wherein the liquid adhesive can be cured by exposure to ultraviolet radiation.

28. (withdrawn) The method of claim 21, wherein the liquid adhesive can be cured by any one of a plurality of curing methods, wherein the first cure comprises applying a first curing method of the plurality of curing methods to the liquid adhesive and wherein the second cure comprises applying a second, different curing method of the plurality of curing methods to the liquid adhesive.